



IC Packaging Markets

2014 Global Report Series

Complex multi-component packages have added a new dimension to high speed integrated circuits (ICs) and their small form factor, thus making them game changers for the industry. It is the package of the IC which holds the device footprint to the printed circuit board (PCB), thereby enabling a multitude of small, handheld electronics computing and communicating products to be invented and proliferate in today's world market.

New Venture Research (NVR) is pleased to announce its continuing coverage of the IC packaging market with two reports in 2014, *The Worldwide IC Packaging Market*, and *Advanced IC Packaging Technologies, Materials, and Markets*. Each report has a different focus, thus allowing the user to analyze the IC packaging market from a number of angles, and combine that information to meet individual research needs.

The first report, **The Worldwide IC Packaging Market**, presents NVR's annual forecast for each of the major package families by semiconductor product type (2013-2018). This information is then totaled by package type. The report also presents NVR's continuing, extensive coverage of the packaging contractor market.

The second report, **Advanced IC Packaging Technologies, Materials, and Markets**, analyzes critical advanced IC packaging methods, primarily aimed at the mobile handheld consumer market, while also including some leading material analysis of IC packaging sets.

The IC Packaging series will provide you with an effective tool for assessing your future in this market. Please review each report's summary Table of Contents on the following page.

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Advanced IC Packaging Technologies, Materials, and Markets - 2014 Edition (PDF Only)	\$3,495		
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The Complete Series (both reports including discount)	\$5495		
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The Worldwide IC Packaging Market

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: Economic Outlook/The State of
the Industry

Chapter 4: IC Package Forecast by Product

Chapter 5: IC Package Forecast by Package
Family

Chapter 6: Contract IC Packaging Market

Chapter 7: Packaging Contractor Profiles

Published August 2014, 400+

Advanced IC Packaging Technologies, Materials, and Markets

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: Stacked Packages

Chapter 4: Through Silicon Vias (TSV)

Chapter 5: System in Package (SiP)

Chapter 6: Quad Flat Pack No-Lead
and Fan-In QFN Packages

Chapter 7: Wafer Level Packages (WLPs),
and Fan-Out WLPs

Chapter 8: BGA/LGA/CGA and
FBGA/FLGA Package Solutions

Chapter 9: Interconnection, Wire Bond
Materials, and Flip Chip by I/O
Count, Markets, and Bumps

Chapter 10: Substrates and TBD

Published November 2014, 300+ pages

About the Author

Jerry Watkins is an independent senior analyst with more than 18 years of experience in the field of market research and consulting. He has worked for leading research companies such as Frost & Sullivan, Lucid Information Services, and NSI Research both in management and as a writer. Mr. Watkins has authored many syndicated reports, previously in the telecommunications sector and more recently in the computing and merchant embedded computing industry. He holds three university degrees including a B.A. in History, as well as a M.A. in International Studies.